

HAI LECK HOLDINGS LIMITED
(Company Registration No. 199804461D)
(Incorporated in the Republic of Singapore)

INCREASE IN ISSUED AND PAID-UP CAPITAL IN SUBSIDIARIES

The Board of Directors of Hai Leck Holdings Limited (the “Company”) wishes to announce that on 12 November 2013, three of its wholly-owned subsidiaries had increased their issued and paid up share capital as follows:

- A. Hai Leck Engineering & Construction Pte. Ltd. (“HLEC”) increased its issued and paid up share capital from S\$200,000 to S\$4,000,000 by a further allotment of 3,800,000 ordinary shares at a consideration of S\$3,800,000 by way of cash injection;
- B. Hai Leck Integrated Services Pte. Ltd. (“HLIS”) increased its issued and paid up share capital from S\$2 to S\$2,000,000 by a further allotment of 1,999,998 ordinary shares at a consideration of S\$1,999,998 by way of capitalisation of loan, being intercompany balances payable by HLIS to the Company; and
- C. Hai Leck Services Pte. Ltd. (“HLS”) increased its issued and paid up share capital from S\$2 to S\$2,000,000 by a further allotment of 1,999,998 ordinary shares at a consideration of S\$1,999,998 by way of capitalisation of loan, being intercompany balances payable by HLS to the Company.

(collectively, the “Transactions”)

The Transactions are not expected to have any material financial impact on the Company’s net tangible assets and earnings per share of the Company and its Group for the financial year ending 30 June 2014.

None of the Directors, Substantial Shareholders or Controlling Shareholders of the Company has any interest, directly or indirectly, in the Transactions.

By Order of the Board

Cheng Yao Tong
Chief Executive Officer

12 November 2013